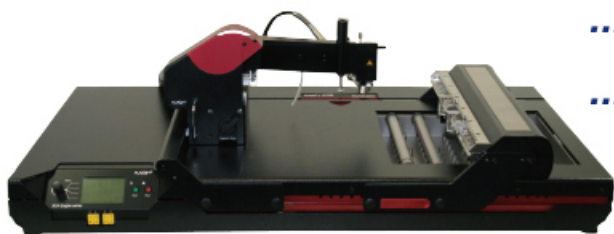


BGA Engine **MaFi-538**

The most powerful BGA rework system

- ... Desoldering a BGA or CSP
- ... Removing old solder and residue
- ... Reballing a BGA or CSP
- ... Positioning and Placing a BGA or CSP
- ... BGA Soldering

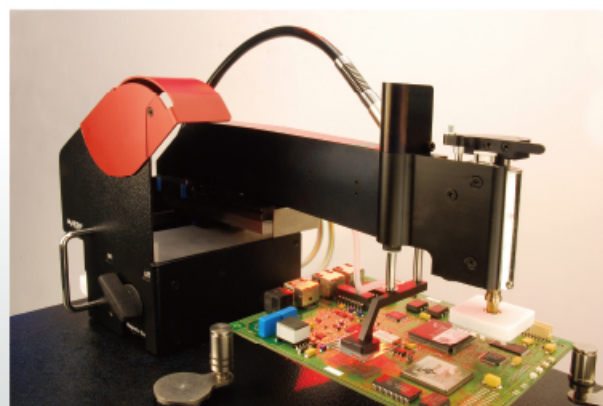


MaFi-538 完美的完成BGA返修之任務, 任意類型, 不同尺寸大小的BGA / Filps chip或是QFN元件都能在極簡易且安全的操作下完成拆 / 迴焊搭載全新雙模底部加熱器後的 **MaFi-538** 不僅能輕易的達成BGA拆焊 / 迴焊同時也能輕鬆的完成除錫 / 植球等全方位返修工作的目標 (獨一無二的視覺對位系統, 配合自動化置放系統造就了市場上精度最高的返修工作站系統)

配合功能強大的雙模底部加熱器與高精準熱風系統, 使用專屬的真空除錫筆更可絲毫不傷Pads的將殘留錫清除一空



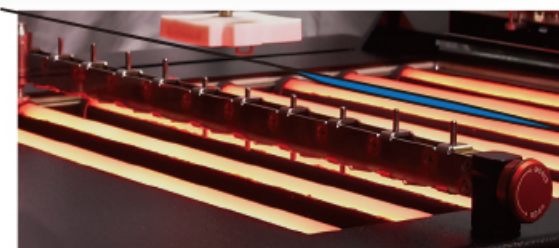
全新雙模底部加熱器



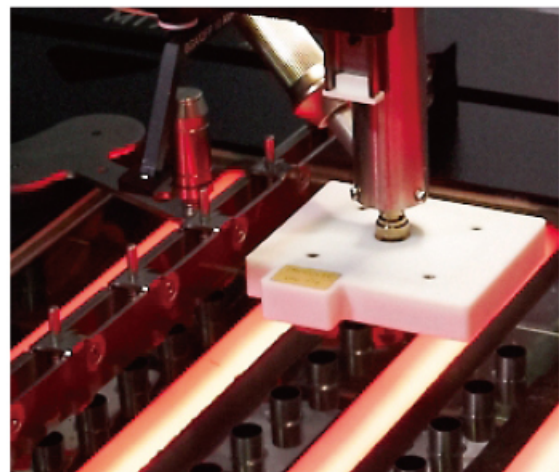
ASP自動對位系統擁有四動向的精準伺服馬達, 搭配星型對位治具, 並用Easy Solder的對位軟體加以精準地控制, 可調整零件位置同時自動放置零件於銅箔上, 是一套簡單、快速的對位系統。

BGA Engine MaFi-538

The most powerful BGA rework system



獨特的底部支撐架, 能夠完美的記憶PCB底部高低起伏之高度差, 如同記憶枕般提供PCB完美的支撐



功能強大的全新雙模底部加熱器, 快速及時且非常均勻的提供底部預熱能量, PCB受熱就像在迴焊爐一般, 保持最低PCB板彎扭曲量

Specification

Power Input	230 V / 50 Hz 25 A
Pressure Input	5.5~8 Bar
Hot air power output	10~250 W / 24 V
Hot air volume	2.0~35 L / Min
Hot air temp	150~400 °C ± 1%
Underheater power	600~3000 W
Underheater size	245 x 275 mm
PCB size	390 x 500 mm
Placement stroke	X-Y-Z / 75-75-40 mm
Placement angle	± 10 °
PCB clipping	smart clip
PCB supporting	Flex Fix pin bar supporter (optional)
Weight	approx. 70 Kg
Communication Link	USB
Program software	Easy Solder
Thermo sensors	2 + 4 Channels
Hot air nozzle	CSP 4 pieces (covering all specs) optional
(all nozzles are optional)	BGA15 / 16 / 17 / 19 / 21 / 23 / 25 / 27 / 29 / 31 / 32 / 33 / 35 / 37.5 / 40 / 40.5 / 45 / 46mm... Socket 478B / 775 / 1207 / 1165 / 1366 / 1567

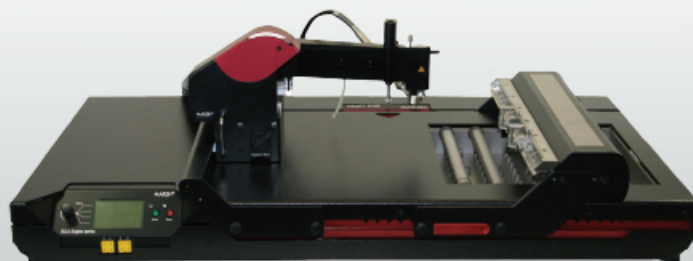
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MaFi-538 BGA Engine